

# China Semiconductor Packaging and Assembly Equipment Market Research Report 2016

<https://marketpublishers.com/r/C47EB2ACD0AEN.html>

Date: November 2016

Pages: 104

Price: US\$ 3,200.00 (Single User License)

ID: C47EB2ACD0AEN

## Abstracts

### Notes:

Sales, means the sales volume of Semiconductor Packaging and Assembly Equipment

Revenue, means the sales value of Semiconductor Packaging and Assembly Equipment

This report studies Semiconductor Packaging and Assembly Equipment in China market, focuses on the top players in China market, with capacity, production, price, revenue and market share for each manufacturer, covering

Applied Materials

ASM Pacific Technology (ASMPT)

Disco

EV Group (EVG)

Kulicke and Soffa Industries

Tokyo Electron Ltd. (TEL)

Tokyo Seimitsu

Rudolph Technologies

## SEMES

Suss Microtec

Split by product Type, with production, revenue, price, market share and growth rate of each type, can be divided into

Die-level packaging and assembly equipment

Wafer-level packaging and assembly equipment

Type III

Split by Application, this report focuses on consumption, market share and growth rate of Semiconductor Packaging and Assembly Equipment in each application, can be divided into

Application 1

Application 2

Application 3

## Contents

### China Semiconductor Packaging and Assembly Equipment Market Research Report 2016

#### **1 SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MARKET OVERVIEW**

- 1.1 Product Overview and Scope of Semiconductor Packaging and Assembly Equipment
- 1.2 Semiconductor Packaging and Assembly Equipment Segment by Type
  - 1.2.1 China Production Market Share of Semiconductor Packaging and Assembly Equipment Type in 2015
  - 1.2.2 Die-level packaging and assembly equipment
  - 1.2.3 Wafer-level packaging and assembly equipment
  - 1.2.4 Type III
- 1.3 Applications of Semiconductor Packaging and Assembly Equipment
  - 1.3.1 Semiconductor Packaging and Assembly Equipment Consumption Market Share by Application in 2015
  - 1.3.2 Application
  - 1.3.3 Application
  - 1.3.4 Application
- 1.4 China Market Size (Value) of Semiconductor Packaging and Assembly Equipment (2011-2021)
- 1.5 China Semiconductor Packaging and Assembly Equipment Status and Outlook
- 1.6 Government Policies

#### **2 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MARKET COMPETITION BY MANUFACTURERS**

- 2.1 China Semiconductor Packaging and Assembly Equipment Capacity, Production and Share by Manufacturers (2015 and 2016)
- 2.2 China Semiconductor Packaging and Assembly Equipment Revenue and Share by Manufacturers (2015 and 2016)
- 2.3 China Semiconductor Packaging and Assembly Equipment Average Price by Manufacturers (2015 and 2016)
- 2.4 Manufacturers Semiconductor Packaging and Assembly Equipment Manufacturing Base Distribution, Sales Area, Product Type
- 2.5 Semiconductor Packaging and Assembly Equipment Market Competitive Situation

and Trends

2.5.1 Semiconductor Packaging and Assembly Equipment Market Concentration Rate

2.5.2 Semiconductor Packaging and Assembly Equipment Market Share of Top 3 and Top 5 Manufacturers

### **3 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MANUFACTURERS PROFILES/ANALYSIS**

3.1 Applied Materials

3.1.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.1.2 Semiconductor Packaging and Assembly Equipment Product Type, Application and Specification

3.1.2.1 Type I

3.1.2.2 Type II

3.1.3 Applied Materials Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.1.4 Main Business/Business Overview

3.2 ASM Pacific Technology (ASMPT)

3.2.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.2.2 104 Product Type, Application and Specification

3.2.2.1 Type I

3.2.2.2 Type II

3.2.3 ASM Pacific Technology (ASMPT) 104 Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.2.4 Main Business/Business Overview

3.3 Disco

3.3.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.3.2 108 Product Type, Application and Specification

3.3.2.1 Type I

3.3.2.2 Type II

3.3.3 Disco 108 Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.3.4 Main Business/Business Overview

3.4 EV Group (EVG)

3.4.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

- 3.4.2 Nov Product Type, Application and Specification
  - 3.4.2.1 Type I
  - 3.4.2.2 Type II
- 3.4.3 EV Group (EVG) Nov Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
- 3.4.4 Main Business/Business Overview
- 3.5 Kulicke and Soffa Industries
  - 3.5.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.5.2 Product Type, Application and Specification
    - 3.5.2.1 Type I
    - 3.5.2.2 Type II
  - 3.5.3 Kulicke and Soffa Industries Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.5.4 Main Business/Business Overview
- 3.6 Tokyo Electron Ltd. (TEL)
  - 3.6.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.6.2 Million USD Product Type, Application and Specification
    - 3.6.2.1 Type I
    - 3.6.2.2 Type II
  - 3.6.3 Tokyo Electron Ltd. (TEL) Million USD Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.6.4 Main Business/Business Overview
- 3.7 Tokyo Seimitsu
  - 3.7.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.7.2 Machinery & Equipment Product Type, Application and Specification
    - 3.7.2.1 Type I
    - 3.7.2.2 Type II
  - 3.7.3 Tokyo Seimitsu Machinery & Equipment Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.7.4 Main Business/Business Overview
- 3.8 Rudolph Technologies
  - 3.8.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.8.2 Product Type, Application and Specification
    - 3.8.2.1 Type I
    - 3.8.2.2 Type II

3.8.3 Rudolph Technologies Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.8.4 Main Business/Business Overview

3.9 SEMES

3.9.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.9.2 Product Type, Application and Specification

3.9.2.1 Type I

3.9.2.2 Type II

3.9.3 SEMES Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.9.4 Main Business/Business Overview

3.10 Suss Microtec

3.10.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.10.2 Product Type, Application and Specification

3.10.2.1 Type I

3.10.2.2 Type II

3.10.3 Suss Microtec Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.10.4 Main Business/Business Overview

#### **4 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT CAPACITY, PRODUCTION, REVENUE, CONSUMPTION, EXPORT AND IMPORT (2011-2016)**

4.1 China Semiconductor Packaging and Assembly Equipment Capacity, Production and Growth (2011-2016)

4.2 China Semiconductor Packaging and Assembly Equipment Revenue and Growth (2011-2016)

4.3 China Semiconductor Packaging and Assembly Equipment Production, Consumption, Export and Import (2011-2016)

#### **5 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT PRODUCTION, REVENUE (VALUE), PRICE TREND BY TYPE**

5.1 China Semiconductor Packaging and Assembly Equipment Production and Market Share by Type (2011-2016)

5.2 China Semiconductor Packaging and Assembly Equipment Revenue and Market

Share by Type (2011-2016)

5.3 China Semiconductor Packaging and Assembly Equipment Price by Type (2011-2016)

5.4 China Semiconductor Packaging and Assembly Equipment Production Growth by Type (2011-2016)

## **6 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MARKET ANALYSIS BY APPLICATION**

6.1 China Semiconductor Packaging and Assembly Equipment Consumption and Market Share by Application (2011-2016)

6.2 China Semiconductor Packaging and Assembly Equipment Consumption Growth Rate by Application (2011-2016)

6.3 Market Drivers and Opportunities

6.3.1 Potential Application

6.3.2 Emerging Markets/Countries

## **7 SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MANUFACTURING COST ANALYSIS**

7.1 Semiconductor Packaging and Assembly Equipment Key Raw Materials Analysis

7.1.1 Key Raw Materials

7.1.2 Price Trend of Key Raw Materials

7.1.3 Key Suppliers of Raw Materials

7.1.4 Market Concentration Rate of Raw Materials

7.2 Proportion of Manufacturing Cost Structure

7.2.1 Raw Materials

7.2.2 Labor Cost

7.2.3 Manufacturing Expenses

7.3 Manufacturing Process Analysis of Semiconductor Packaging and Assembly Equipment

## **8 INDUSTRIAL CHAIN, SOURCING STRATEGY AND DOWNSTREAM BUYERS**

8.1 Semiconductor Packaging and Assembly Equipment Industrial Chain Analysis

8.2 Upstream Raw Materials Sourcing

8.3 Raw Materials Sources of Semiconductor Packaging and Assembly Equipment Major Manufacturers in 2015

8.4 Downstream Buyers

## **9 MARKETING STRATEGY ANALYSIS, DISTRIBUTORS/TRADERS**

- 9.1 Marketing Channel
  - 9.1.1 Direct Marketing
  - 9.1.2 Indirect Marketing
  - 9.1.3 Marketing Channel Development Trend
- 9.2 Market Positioning
  - 9.2.1 Pricing Strategy
  - 9.2.2 Brand Strategy
  - 9.2.3 Target Client
- 9.3 Distributors/Traders List

## **10 MARKET EFFECT FACTORS ANALYSIS**

- 10.1 Technology Progress/Risk
  - 10.1.1 Substitutes Threat
  - 10.1.2 Technology Progress in Related Industry
- 10.2 Consumer Needs/Customer Preference Change
- 10.3 Economic/Political Environmental Change

## **11 CHINA SEMICONDUCTOR PACKAGING AND ASSEMBLY EQUIPMENT MARKET FORECAST (2016-2021)**

- 11.1 China Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue Forecast (2016-2021)
- 11.2 China Semiconductor Packaging and Assembly Equipment Production, Import, Export and Consumption Forecast (2016-2021)
- 11.3 China Semiconductor Packaging and Assembly Equipment Production Forecast by Type (2016-2021)
- 11.4 China Semiconductor Packaging and Assembly Equipment Consumption Forecast by Application (2016-2021)
- 11.5 Semiconductor Packaging and Assembly Equipment Price Forecast (2016-2021)

## **12 RESEARCH FINDINGS AND CONCLUSION**

## **13 APPENDIX**

Author List



Disclosure Section  
Research Methodology  
Data Source  
China Disclaimer

## List Of Tables

### LIST OF TABLES AND FIGURES

Figure Picture of Semiconductor Packaging and Assembly Equipment

Figure China Production Market Share of Semiconductor Packaging and Assembly Equipment by Type in 2015

Figure Product Picture of Die-level packaging and assembly equipment

Table Major Manufacturers of Die-level packaging and assembly equipment

Figure Product Picture of Wafer-level packaging and assembly equipment

Table Major Manufacturers of Wafer-level packaging and assembly equipment

Figure Product Picture of Type III

Table Major Manufacturers of Type III

Table Semiconductor Packaging and Assembly Equipment Consumption Market Share by Application in 2015

Figure Application 1 Examples

Figure Application 2 Examples

Figure Application 3 Examples

Figure China Semiconductor Packaging and Assembly Equipment Revenue (Million USD) and Growth Rate (2011-2021)

Table China Semiconductor Packaging and Assembly Equipment Capacity of Key Manufacturers (2015 and 2016)

Table China Semiconductor Packaging and Assembly Equipment Capacity Market Share of Key Manufacturers (2015 and 2016)

Figure China Semiconductor Packaging and Assembly Equipment Capacity of Key Manufacturers in 2015

Figure China Semiconductor Packaging and Assembly Equipment Capacity of Key Manufacturers in 2016

Table China Semiconductor Packaging and Assembly Equipment Production of Key Manufacturers (2015 and 2016)

Table China Semiconductor Packaging and Assembly Equipment Production Share by Manufacturers (2015 and 2016)

Figure 2015 Semiconductor Packaging and Assembly Equipment Production Share by Manufacturers

Figure 2016 Semiconductor Packaging and Assembly Equipment Production Share by Manufacturers

Table China Semiconductor Packaging and Assembly Equipment Revenue (Million USD) by Manufacturers (2015 and 2016)

Table China Semiconductor Packaging and Assembly Equipment Revenue Share by

Manufacturers (2015 and 2016)

Table 2015 China Semiconductor Packaging and Assembly Equipment Revenue Share by Manufacturers

Table 2016 China Semiconductor Packaging and Assembly Equipment Revenue Share by Manufacturers

Table China Market Semiconductor Packaging and Assembly Equipment Average Price of Key Manufacturers (2015 and 2016)

Figure China Market Semiconductor Packaging and Assembly Equipment Average Price of Key Manufacturers in 2015

Table Manufacturers Semiconductor Packaging and Assembly Equipment Manufacturing Base Distribution and Sales Area

Table Manufacturers Semiconductor Packaging and Assembly Equipment Product Type

Figure Semiconductor Packaging and Assembly Equipment Market Share of Top 3 Manufacturers

Figure Semiconductor Packaging and Assembly Equipment Market Share of Top 5 Manufacturers

Table Applied Materials Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Applied Materials Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Applied Materials Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table ASM Pacific Technology (ASMPT) Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table ASM Pacific Technology (ASMPT) Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure ASM Pacific Technology (ASMPT) Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Disco Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Disco Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Disco Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table EV Group (EVG) Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table EV Group (EVG) Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure EV Group (EVG) Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Kulicke and Soffa Industries Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Kulicke and Soffa Industries Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Kulicke and Soffa Industries Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Tokyo Electron Ltd. (TEL) Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Tokyo Electron Ltd. (TEL) Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Tokyo Electron Ltd. (TEL) Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Tokyo Seimitsu Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Tokyo Seimitsu Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Tokyo Seimitsu Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Rudolph Technologies Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Rudolph Technologies Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Rudolph Technologies Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table SEMES Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table SEMES Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure SEMES Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Table Suss Microtec Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Suss Microtec Semiconductor Packaging and Assembly Equipment Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Suss Microtec Semiconductor Packaging and Assembly Equipment Market Share (2011-2016)

Figure China Semiconductor Packaging and Assembly Equipment Capacity, Production and Growth (2011-2016)

Figure China Semiconductor Packaging and Assembly Equipment Revenue (Million USD) and Growth (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Production, Consumption, Export and Import (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Production by Type (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Production Share by Type (2011-2016)

Figure Production Market Share of Semiconductor Packaging and Assembly Equipment by Type (2011-2016)

Figure 2015 Production Market Share of Semiconductor Packaging and Assembly Equipment by Type

Table China Semiconductor Packaging and Assembly Equipment Revenue by Type (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Revenue Share by Type (2011-2016)

Figure Production Revenue Share of Semiconductor Packaging and Assembly Equipment by Type (2011-2016)

Figure 2015 Revenue Market Share of Semiconductor Packaging and Assembly Equipment by Type

Table China Semiconductor Packaging and Assembly Equipment Price by Type (2011-2016)

Figure China Semiconductor Packaging and Assembly Equipment Production Growth by Type (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Consumption by Application (2011-2016)

Table China Semiconductor Packaging and Assembly Equipment Consumption Market Share by Application (2011-2016)

Figure China Semiconductor Packaging and Assembly Equipment Consumption Market Share by Application in 2015

Table China Semiconductor Packaging and Assembly Equipment Consumption Growth Rate by Application (2011-2016)

Figure China Semiconductor Packaging and Assembly Equipment Consumption Growth Rate by Application (2011-2016)

Table Production Base and Market Concentration Rate of Raw Material

Figure Price Trend of Key Raw Materials

Table Key Suppliers of Raw Materials

Figure Manufacturing Cost Structure of Semiconductor Packaging and Assembly Equipment

Figure Manufacturing Process Analysis of Semiconductor Packaging and Assembly Equipment

Figure Semiconductor Packaging and Assembly Equipment Industrial Chain Analysis  
Table Raw Materials Sources of Semiconductor Packaging and Assembly Equipment  
Major Manufacturers in 2015

Table Major Buyers of Semiconductor Packaging and Assembly Equipment

Table Distributors/Traders List

Figure China Semiconductor Packaging and Assembly Equipment Capacity, Production and Growth Rate Forecast (2016-2021)

Figure China Semiconductor Packaging and Assembly Equipment Revenue and Growth Rate Forecast (2016-2021)

Table China Semiconductor Packaging and Assembly Equipment Production, Import, Export and Consumption Forecast (2016-2021)

Table China Semiconductor Packaging and Assembly Equipment Production Forecast by Type (2016-2021)

Table China Semiconductor Packaging and Assembly Equipment Consumption Forecast by Application (2016-2021)

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